



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A-0602-04R1 DATE: 21-Jun-2006		MEANS OF DISTINGUISHING CHANGED DEVICES:	
Product Affected: Products built in 655L 24.5x19.5mm FCBGA. Refer to the attached list for the affected part numbers.		☐ Product Mark	Lot # will have "B" prefix
Date Effective: 14-Jun-2006		☒ Back Mark	
		☐ Date Code	
		☐ Other	
Contact: Geoffrey Cortes			
Title: Product Quality Assurance		Attachment: ☒ Yes ☐ No	
Phone #: (408) 284-8321			
Fax #: (408) 284-1450		Samples: Please contact your local sales representative for sample request & availability.	
E-mail: Geoffrey.Cortes@idt.com			
DESCRIPTION AND PURPOSE OF CHANGE:			
☐ Die Technology		This notification is to amend solder ball composition that was inadvertently written as 95.5Sn/4Ag/0.5Cu in PCN# A-0602-04, published in 16-Mar-2006.	
☐ Wafer Fabrication Process			
☐ Assembly Process		The correct solder ball composition is 96.5Sn/3Ag/0.5Cu.	
☐ Equipment			
☐ Material		There is no change in the PCN affectivity date.	
☐ Testing			
☒ Manufacturing Site			
☐ Data Sheet			
☐ Other			
RELIABILITY/QUALIFICATION SUMMARY:			
There is no expected change to the product quality or reliability performance.			
CUSTOMER ACKNOWLEDGMENT OF RECEIPT:			
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.			
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.			
Customer: _____		☐ <i>Approval for shipments prior to effective date.</i>	
Name/Date: _____		E-Mail Address: _____	
Title: _____		Phone# /Fax# : _____	
CUSTOMER COMMENTS: _____			
IDT ACKNOWLEDGMENT OF RECEIPT:			
RECD. BY: _____		DATE: _____	



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ATTACHMENT I - PCN # : A-0602-04R1

PCN Type: Manufacturing Site - Alternate Assembly Location
Data Sheet Change: None
No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT has qualified STATSChipPAC in Korea as an alternate assembly facility for 655L, 24.5x19.5mm FCBGA package using the assembly material set as listed in the Table 1.

There is no change in the moisture sensitive level (MSL) as a result of this change.

Attachment I outlines the qualification data and the affected part # list.

A revised PCN is being issued to correct the solder ball composition. Please refer to Table 1 for details.

Table 1

Description	Existing	Add
Assembly Location	Amkor, Philippines and Korea	STATSChipPAC, Korea
Assembly Material	95Pb/5Sn (High Pb bump), NAU6 (Underfill), 96.5Sn/3Ag/0.5Cu (Solder Ball)	95Pb/5Sn (High Pb bump), CRP-4152RA (Underfill), 96.5Sn/3Ag/0.5Cu (Solder Ball)

Sample Availability:

Samples are already available for customer evaluation.

Please contact your local IDT sales representative for your sample request and availability.



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Qualification Information and Qualification Tests Result:

Test Vehicles: **1681L, 42.5mm FCBGA (3 assembly lots)**

Test Description	Test Method	Sample Size / # of Fails	Test Results (SS/Rej)
* Temperature Cycling (Cond B, 1000 cycles)	JESD22-A104-B	45/0	45/0
* HAST (130°C/85% RH, unbiased, 100 hours)	JESD22-A102-C	45/0	45/0
** High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103-C	77/0	77/0

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113C.
 ** One assembly lot

Affected Part #s

IDTAMB0480A5RH
IDTAMB0480A5RJ